

ABSTRACT

The resin composition for encapsulating semiconductor of the present invention is a resin composition for encapsulating semiconductor including an epoxy resin, a curing agent, an inorganic filler, and carbon black fine particles, in which when the resin composition for encapsulating semiconductor is injection-molded to have a length of 80 mm, a width of 10 mm and a thickness of 4 mm under conditions of a mold temperature of 175°C, an injection pressure of 10 MPa, and a curing time of 120 seconds, and then heated at 175°C for 4 hours to obtain a cured product, and then a surface of the obtained cured product is observed with a fluorescence microscope, a maximum particle diameter of aggregates of the carbon black fine particles is 50 μm or less.

FIG. 1